

ABSTRACT

This invention relates to a negative-working photosensitive resin composition that can be developed in an alkaline developer. This photosensitive resin composition comprises: (a) a polyimide having at least one group selected from the group consisting of a carboxyl group, a phenolic hydroxyl group, a sulfonic acid group, and a thiol group at the terminus of the polymer main chain; (b) a compound having a polymerizable functional group comprising unsaturated double and/or triple bonds; and (c) a photopolymerization initiator.